

TERMINAL PAD SOLDERABILITY:
 Meets EIA Specification RS186-9E
 And ANSI/J-STD-002 Category 3.

TERMINAL PAD MATERIALS:

Gold-Plated Nickel-Copper
 Lead-Free, ROHS Compliant

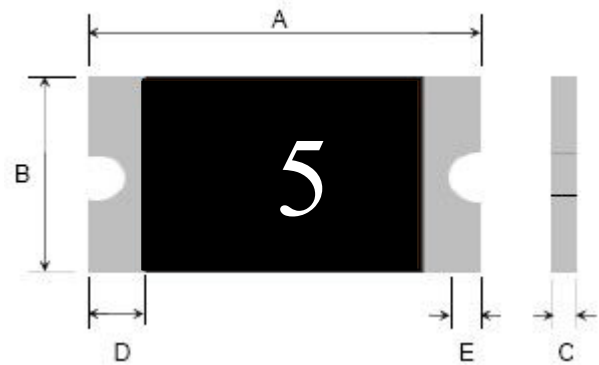


TABLE I. DIMENSIONS:

Unit: mm

Model	Marking	A		B		C		D		E
		Min	Max	Min	Max	Min	Max	Min	Min	
SMD0805-050	5	2.00	2.20	1.20	1.50	0.30	0.60	0.20	0.10	

TABLE II. PERFORMANCE RATINGS:

Model	-Vmax	I _{max}	I _{hold@25°C}	I _{trip@25°C}	P _d Typ.	Maximum Time TO Trip		Resistance		
	(Vdc)	(A)	(A)	(A)	(W)	Current (A)	Time (Sec)	R _{imin} (Ω)	R _{ityp} (Ω)	R _{imax} (Ω)
SMD0805-050	6.0	100	0.50	1.00	0.50	8.0	0.10	0.150	0.420	0.850

Note:

I_{hold}=Hold current:maximum current device will pass without tripping in 23°C still air.

I_{trip}=Trip current:minimum current at which the device will trip in 23°C still air.

V_{max}=Maximum voltage device can withstand without damage at rated curre (I_{max}) .

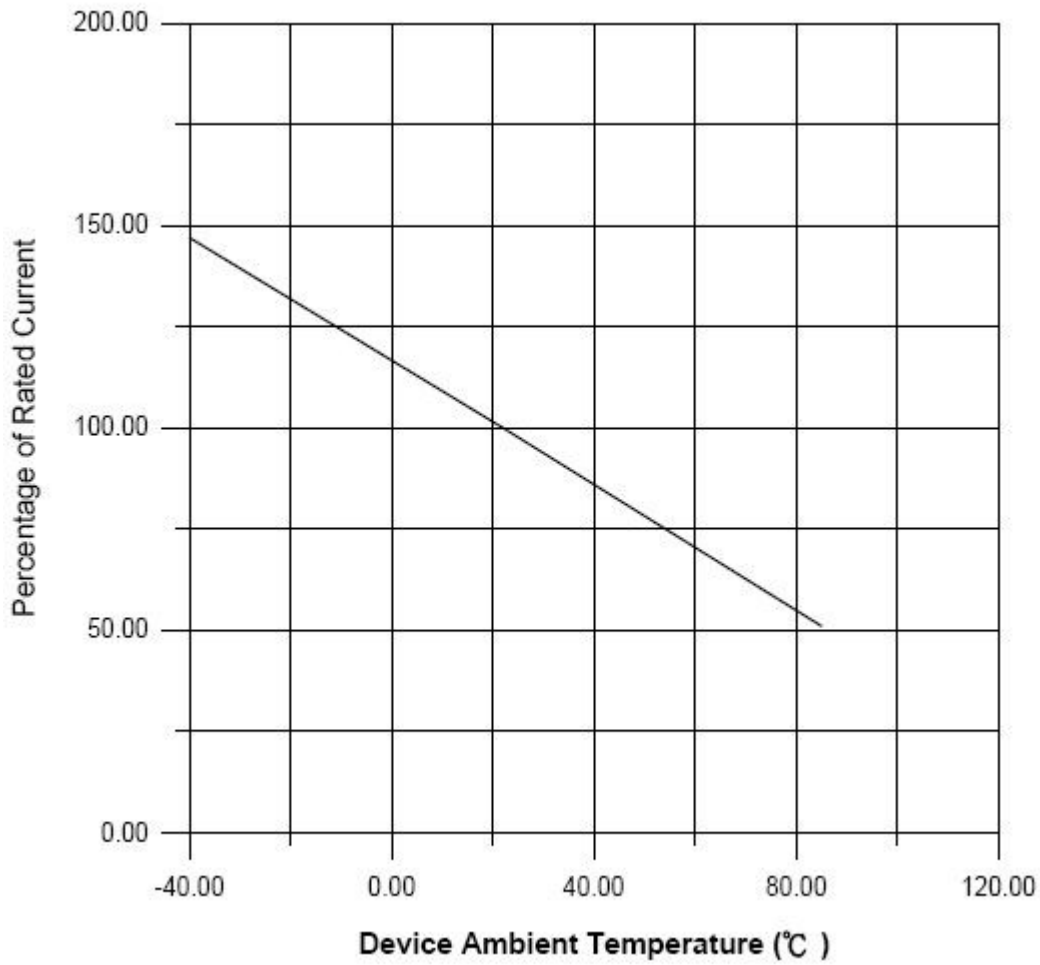
I_{max}=Maximum fault current device can withstand without damage at rated v (V_{max}) .

P_d=Power dissipated from device when in the tripped state at 23°C still air.

R_{min}=Minimum resistance of device in initial (un-soldered) state.

R_{1max}=Maximum resistance of device at 23°C measured one hour after tripping or reflow soldering of 260°C for 20sec.

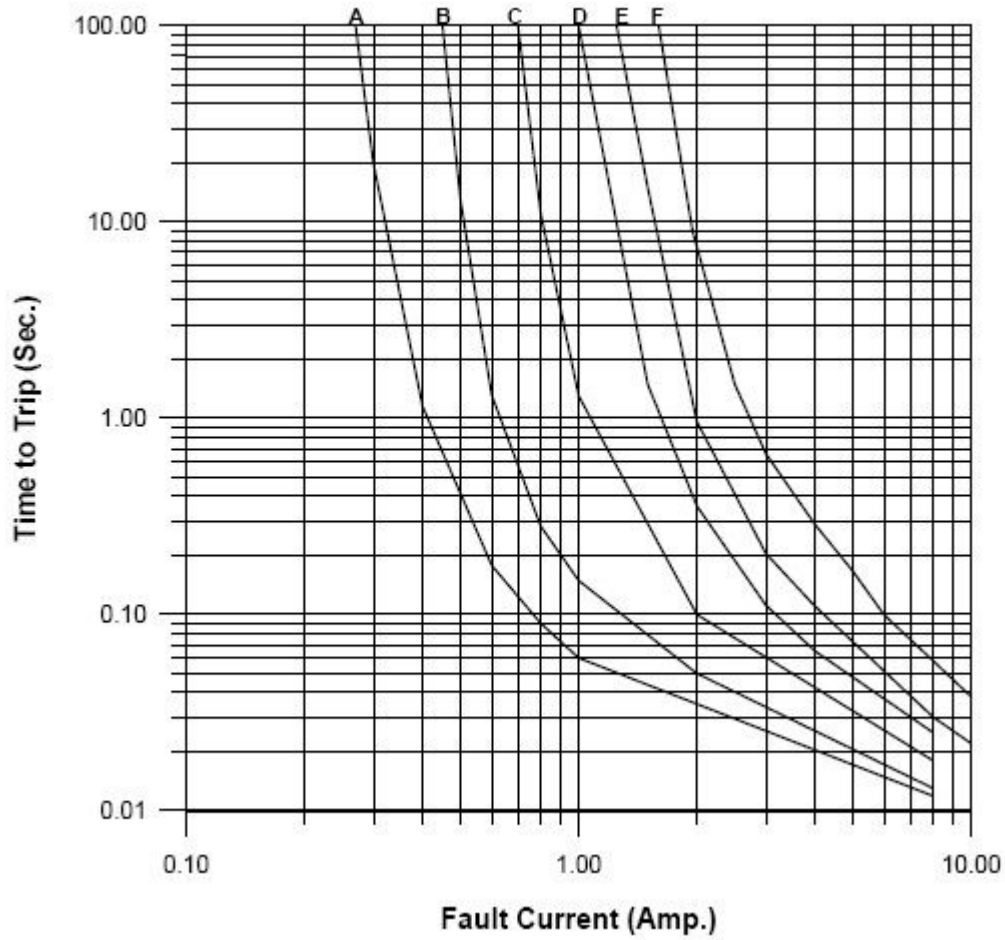
THERMAL DERATING CURVE FOR SMD0805 SERIES



**THERMAL DERATING CHART FOR SMD0805 SERIES-IHOLD(Amps)
RECOMMENDED DATA**

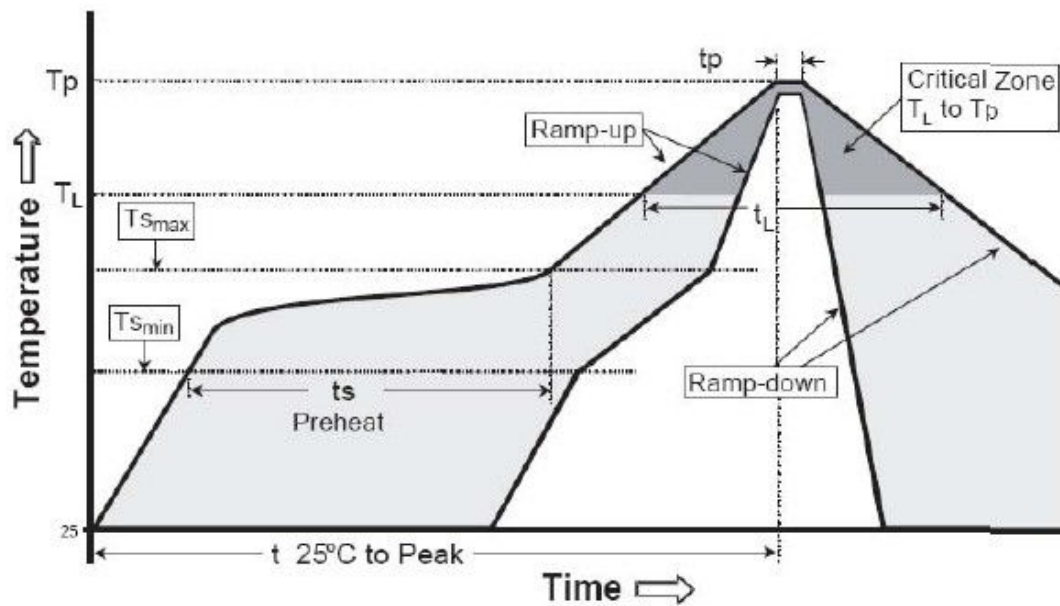
Model	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
SMD0805P050	0.68	0.62	0.55	0.50	0.40	0.37	0.33	0.29	0.23

AVERAGE TIME-CURRENT CURVE FOR SMD0805 SERIES



- A-SMD0805P010
- B-SMD0805P020
- C-SMD0805P035
- D-SMD0805P050
- E-SMD0805P075
- F-SMD0805P100
- SMD0805P110

SOLDER REFLOW



RECOMMENDED CONCITIONS

Profile Feature	Pd-Free Assembly
Average Ramp-Up Rate(Tsmax to Tp)	3°C/second max
Preheat —Temperature Min(Tsmin) —Temperature Max(Tsmax) —Time(Tsmin to Tsmax)	150°C 200°C 60-180seconds
Time maintained above: —Temperature(TL) —Time(tL)	217°C 60-150seconds
Peak Temperature(Tp)	260°C
Time within 5°C of actual Peak Temperature(tp)	20-40seconds
Ramp-Down Rate	6°C/second max.
Time 25°C to Peak Temperature	8minutes max.
Storage Condition	0°C~35°C, ≤70%RH

Note: 1.All temperature refer to topside of the package, measured on the package body surface.
2.If reflow temperature exceed the recommended profile, devices

PACKAGING

Part Number	Component Package	Quantity
SMD0805-050	0805	5000